

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT7131097

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ATSUKO ENOMOTO	01/10/2022
YUTA YAMAUCHI	11/16/2020
REIKO INOUE	11/12/2020
RECEIVING PARTY DATA	
Name:	HITACHI, LTD.
Street Address:	6-6, MARUNOUCHI 1-CHOME, CHIYODA-KU
City:	TOKYO
State/Country:	JAPAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16899723
CORRESPONDENCE DATA	
Fax Number:	(703)684-1157
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(703) 648-1120
Email:	bvillatoro@mmiplaw.com, docket@mmiplaw.com
Correspondent Name:	MATTINGLY & MALUR PC
Address Line 1:	1800 DIAGONAL ROAD
Address Line 2:	SUITE 210
Address Line 4:	ALEXANDRIA, VIRGINIA 22314
ATTORNEY DOCKET NUMBER:	TOU-12681
NAME OF SUBMITTER:	JOHN MATTINGLY
SIGNATURE:	/John Mattingly/
DATE SIGNED:	01/20/2022
Total Attachments: 3	
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ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by Hitachi, Ltd., a corporation organized under the laws of Japan, located at 6-6, Marunouchi 1-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi, Ltd., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

ASSEMBLY PLANNING DEVICE, ASSEMBLY PLANNING METHOD, AND NON-TRANSITORY COMPUTER-READABLE STORAGE MEDIUM

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi, Ltd., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi, Ltd.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) _____ Atsuko ENOMOTO _____	_____
2) <u>Yuta Yamauchi</u> Yuta YAMAUCHI _____	<u>11/16 / 2020</u> _____
3) _____ Reiko INOUE _____	_____
4) _____	_____
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____

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And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

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Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) _____ Atsuko ENOMOTO _____	_____
2) _____ Yuta YAMAUCHI _____	_____
3) <u>Reiko Inoue</u> _____ Reiko INOUE _____	<u>11/12/2020</u> _____
4) _____	_____
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____